Trizeps SODIMM SOM

Trizeps VII SX

SODIMM-200 CPU-Module with NXP i.MX 6SoloX Application Processor

i.MX6 CPU module with with 2 Ethernet interfaces and additional Cortex M4 co-processor



HIGHLIGHTS

CPU
NXP i.MX 6SoloX, Single core Cortex®-A9 @ 1GHz + Cortex®-M4 core @ 227MHz

CONNECTIVITY
2x Fast Ethernet, WiFi/Bluetooth, USB 2.0, PCIe

GRAPHICS
Vivante GC400T, 2D and 3D HW accelerator

MEMORY
Up to 2 GB LPDDR3-533 RAM memory, 32 Bit

Available in Industrial Temperature Range

GOLD PARTNER NXP

AI-ENABLED WITH CLEA

Windows Embedded Compact 7 | Linux

MAIN FIELDS OF APPLICATION

Automation | Biomedical/ Medical devices | Digital signage - Infotainment | Edge Computing | Energy | HMI | Home Automation | Industrial Automation and Control | Info Kiosks | Measuring instruments | Point of Sales | Portable devices | Thin clients | Vending

FEATURES

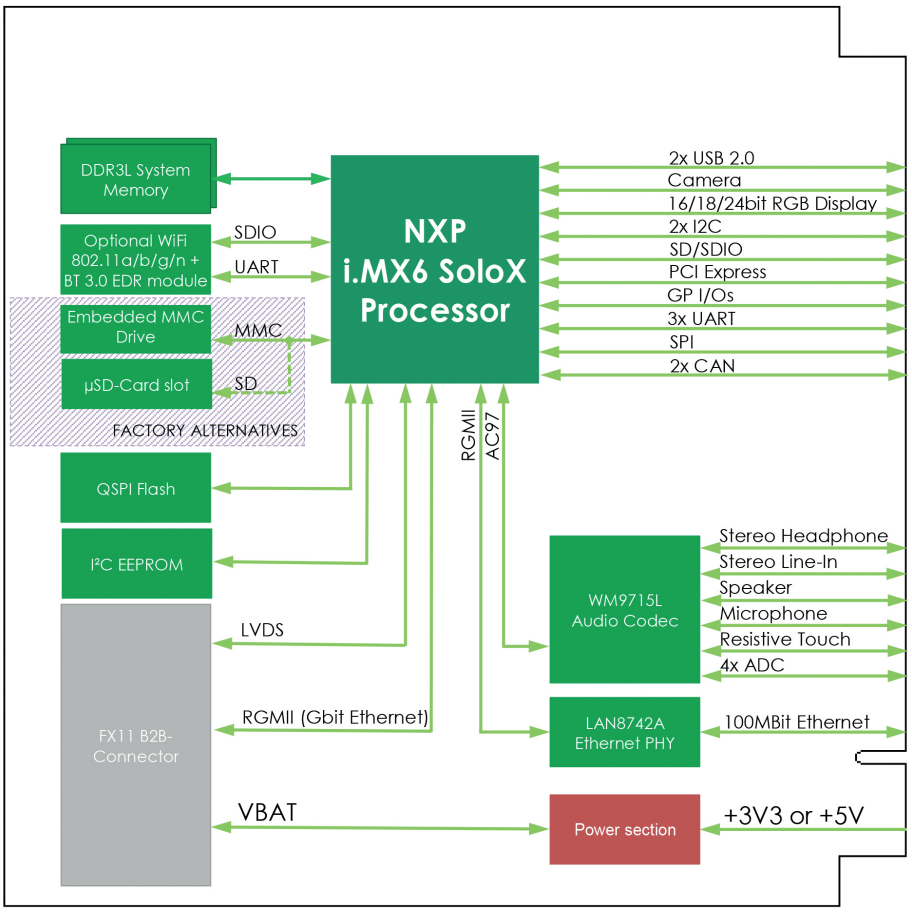
Processor	NXP i.MX 6SoloX, SingleCore Cortex®-A9 @ 1GHz, Cortex®-M4 core @ 227MHz
Memory	Soldered down LPDDR3-533 memory up to 2 GB, 32-bit interface
Graphics	Vivante GC400T, 2D and 3D HW accelerator OpenGL ES 2.0, OpenGL ES 1.1, OpenVG 1.1 supported
Video Interfaces	LVDS, LCD 24 Bit RGB
Video Resolution	LVDS: up to 1366x768 @60Hz RGB: up to 1920x1080p @60Hz
Mass Storage	Onboard 4 Bit wide µSD Card Socket or onboard 8 Bit wide eMMC
Networking	1x 100 Mbit Ethernet RGMII PHY and 1x 1000 Mbit Ethernet RGMII interface, can be used at the same time Optional: WiFi 802.11 a/b/g/n/e/i/h/d/k/r/w, Bluetooth 3.0+ EDR
USB	1x USB 2.0 OTG and 1x USB 2.0 Host
PCI-e	1 x PCI-e
Audio	AC'97 Audio Codec with 4/5 wires res. Touch and 4x 12 Bit ADC (2x comparator inputs for battery monitoring); Stereo: Line-in, Mic-in, Speaker-out, Headphone out
Serial Ports	3x UART

Other Interfaces	2x FlexCAN S-ATAII 2x 4 Bit wide SDIO RTC SPDIF Adress-Data-Bus 2x I2C 2x SPI GPIOs 2x PWM
Power Supply	3.3 VDC (SODIMM) + 5 VDC and battery (FX11)
Operating System	Windows Embedded Compact 7, 2013 Linux
Operating Temperature*	-40 ÷ 85°C (industrial) -20 ÷ 85°C (Extended Consumer) 0 ÷ 70°C (Consumer)
Dimensions	67.6 x 36.7 x 6.4 mm

*All carrier board components must remain within the operating temperature at any and all times, including start-up; carrier operating temperature is independent of the module installed. Please refer to the specific module for more details. Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider specific cooling solutions for the final system.

Information subject to change. Please visit www.edge.seco.com to find the latest version of this datasheet

BLOCK DIAGRAM



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